

ABSTRACT

Provided is a packaging structure for a sensor probe, a sensor probe, a sensor, and a water purifier. The packaging structure for the sensor probe includes a probe and an insulation housing formed at an outer periphery of the probe through a one-step injection molding. Two
5 ends of the probe are located outside the insulation housing. The insulation housing has a through hole extending through two ends of the insulation housing. The through hole is adapted to allow a temperature sensor probe to pass through the through hole. The packaging structure for the sensor probe, the sensor probe, the sensor, and the water purifier provided are capable of reducing the number of injection-molded process times for the sensor probe and improving
10 connection and assembly efficiency between a temperature probe of a temperature sensor and a TDS sensor probe.

Figure 1